L Number	Hits	Search Text	DB	Time stamp
1	33	((recognition\$4 adj mark\$4) with (via or through-hole or (through adj	USPAT;	2003/09/24 17:04
		hole) or throughhole contact bump plated plating)) with (wiring circuit	US-PGPUB;	
		circuity ic socket metal metallization conducting conductive conductor)	EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
_	1429	recognition\$4 adj mark\$4	USPAT;	2003/09/24 16:59
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT,	,
			IBM TDB	
_	77	(recognition\$4 adj mark\$4) with (via or through-hole or (through adj	USPAT;	2003/09/24 16:59
		hole) or throughhole contact bump plated plating)	US-PGPUB:	
		,	EPO; JPO;	
			DERWENT:	
			IBM TDB	